

21052/00

51	51	Class	Subclass
ISSUE CLASSIFICATION			

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U.S. UTILITY Patent Application

7-11-68	Q1P1	PATENT DATE
SCANNED 112	Q1A TW	

APPLICATION NO. 09/945241	CONT/PRIOR F	CLASS 257 438	SUBCLASS 612	ART UNIT 2615 2812	EXAMINER Nguyen, H/C
<p>APPLICANTS</p> <p>Fumiaki Matsushima Tsutomu Ota Akira Makabe</p>					
<p>TITLE</p> <p>Method for forming a bump, semiconductor device and method of fabricating same, semiconductor chip, circuit board, and electronic instrument</p>					

PTO-2040
12/99

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg	Figs. Drwg	Print Fig	Total Claims	Print Claim for O.C.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed. <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____	_____ (Assistant Examiner) _____ (Date)			NOTICE OF ALLOWANCE MAILED	
	_____ (Primary Examiner) _____ (Date)			ISSUE FEE	
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<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) _____ (Date)			ISSUE BATCH NUMBER	

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